

METHOD OF MANUFACTURING SEMICONDUCTOR DEVICE AND WIRE BONDING APPARATUS

ABSTRACT

A method of manufacturing a semiconductor device includes: a wire tail forming step of forming a wire loop 130 between a first bonding point and a second bonding point with a bonding tool 40, and then cutting portion of a wire 42 extending from a tip of the bonding tool 40 to thereby form a wire tail 43 at the tip of the bonding tool 40; and a wire tail bending step of bending the wire tail 43 so as to direct a tip 43a of the wire tail 43 upward by descending the bonding tool 40 toward the second bonding point with the wire loop 130 formed thereat and pressing the wire tail 43 against portion of the wire loop 130 located above the second bonding point. Thus, the wire tail can be bent easily and efficiently.

Fig 3